Application

The mode to handle gases by making gases having hazardous ingredients used in the semiconductor process pass through flames. All types of gases including PFC gas can be handled.

Applied fields

All the processes of semiconductor, etc.

Gases that can be handled

▶ Etching : CF₄, SF₆, CHF₃, Cl₂, BCl₃, HBr, Etc.

▶ CVD: NF₃, SiH₄,TEOS, WF₆, NH₃, Etc.

▶ DIFF: SiH₄, DCS, NH₃, CIF₃, F₂, Etc.

► IMPLANTER: AsH₃, PH₃, BF₃, Etc.

General Features

- ▶ Pressure sensor at waste gas inlet
- ▶ Pressure sensor in the combustion reactor
- ▶ Temperature sensor in the scrubber
- ▶ Temperature sensor in the lye recirculation tank
- Flow sensor for the cabinet exhaust
- Fuel gas leakage sensor in the cabinet
- Leakage sensors in the safety tank
- Independent flame sensors in the combustion reactor
- Flow meters in the scrubber supply





Utility Requirments

ltem	Specification
Dimension	695(W)×840(D)×1880(H)
Electric Power	3Phase, AC208V
Inlet Port	NW40Flange_4Port
LNG	1/2"VCR, 0.3~1.8kgf/cm ²
O ₂	1/2"VCR, 5~6kgf/cm ²
CDA	1/2"LOK, 5~6.5kgf/cm ²
N ₂	1/2"LOK, 4~5kgf/cm ²
PCW	1/2"LOK, 3~6kgf/cm ²
CW	1/2"LOK, 3~6kgf/cm ²
NaOH	1 1/2"DoulbePipe
Exhaust	MF100Flange, -30 ~ -60mmH₂O
Cabinet Exhaust	MF100Flange, -30 ~ -60mmH₂O
Drain	15A(PVC)

Application

The mode to handle gases by making gases having hazardous ingredients used in the semiconductor process pass through flames. All types of gases including PFC gas can be handled.

Applied fields

All the processes of semiconductor, etc.

Gases that can be handled

▶ Etching: CF₄, SF₈, CHF₃, Cl₂, BCl₃, HBr, Etc.

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General Features

- Pressure sensor at waste gas inlet
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- Temperature sensor in the scrubber
- Temperature sensor in the lye recirculation tank
- Flow sensor for the cabinet exhaust
- Fuel gas leakage sensor in the cabinet
- Leakage sensors in the safety tank
- Independent flame sensors in the combustion reactor
- Flow meters in the scrubber supply





Utility Requirments

ltem	Specification
Dimension	1200(W)×855(D)×1880(H)
Electric Power	3Phase, AC208V
Inlet Port	NW25Flange_8Port
LNG	1/2"VCR, 0.3 ~ 1.8kgf/cm ²
O ₂	1/2"VCR, 5 ~ 6kgf/cm ²
CDA	1/2"LOK, 5 ~ 6.5kgf/cm ²
N ₂	1/2"LOK, 3 ~ 6kgf/cm ²
PCW	3/4"LOK, 3 ~ 6kgf/cm ²
CW	3/4"LOK, 3 ~ 6kgf/cm ²
NaOH	1 1/2"DoulbePipe
Exhaust	MF100Flange, -30~ -60mmH ₂ O
Cabinet Exhaust	MF100Flange, -30~ -60mmH ₂ O
Drain	20A(PVC)

Application

A scrubber to handle large capacity gases generated form LCD, LED, SOLAR etc. The mode is to directly oxidize gases having hazardous ingredients. All types of gases including PFC gas can be handled.

Applied fields

All processes of LCD, etc.

Gases that can be handled

▶ Etching : SF₆, Cl₂, HCl, Etc.

► CVD: NF₃, SiH₄, NH₃, PH₃, H₂, Etc.

General Features

- ▶ Independent 6 waste gas inlet
- Multi pressure monitoring & Alarm
- Automatic by-pass valves
- Designed for prevention powder deposition
 Humidity
- ▶ High reliability & High Efficiency
- ▶ Small foot print & Back pressure free
- Multi Temperature Monitor & Alarm
- Multi Pressure Monitoring & Alarm
- ▶ Dual flame sensor
- Anti-corrosion material structure





Utility Requirments

ltem	Specification
Dimension	1250(W)×1100(D)×2122(H)
Electric Power	1 Phase, AC208V
Inlet Port	NW40Flange_6Port
LNG	1/2"VCR, 0.3 ~ 1.8kgf/cm ²
O ₂	1/2"VCR, 5 ~ 6kgf/cm ²
CDA	1/2"LOK, 5 ~ 6.5kgf/cm ²
N ₂	1/2"LOK, 4 ~ 5kgf/cm ²
PCW	3/4"LOK, 3 ~ 6kgf/cm ²
CW	1/2"LOK, 3 ~ 6kgf/cm ²
NaOH	1 1/2"Doulbe Pipe
Exhaust	MF100Flange, -30 ~ -100mmH ₂ O
Cabinet Exhaust	MF100Flange, -30 ~ -60mmH₂O
Drain	20A(PVC)